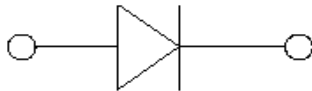


Schottky Barrier Diode



Features

- For Power Supply
- Moisture Sensitivity Level 1
- Low Voltage, Low Inductance

Mechanical Data

- **Package:** SOD323
- **Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- **Polarity:** Cathode line denotes the cathode end
- **Marking:** D

■Maximum Ratings (Ta=25°C Unless otherwise specified)

PARAMETER	SYMBOL	UNIT	Conditions	VALUE
Peak Repetitive Reverse Voltage	V_{RRM}	V		30
DC Blocking Voltage	V_R	V	$I_R = 100\mu A$	20
Non-repetitive Peak forward surge current	I_{FSM}	A	$t_p = 8.3ms$, half sine	2
Average forward current	I_{FAV}	A		0.5
Power Dissipation	P_D	mW		200
Thermal Resisitance Junction to Ambient Air	R_{thja}	°C/W		500
Maximum junction temperature	T_J	°C		125
Storage temperature range	T_{stg}	°C		-55 to +150

*Part mounted on FR-4 board with recommended pad layout.

■Ordering Information (Example)

PREFERRED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
RB551V-30	F2	Approximate 0.0048	3000	30000	120000	7" reel

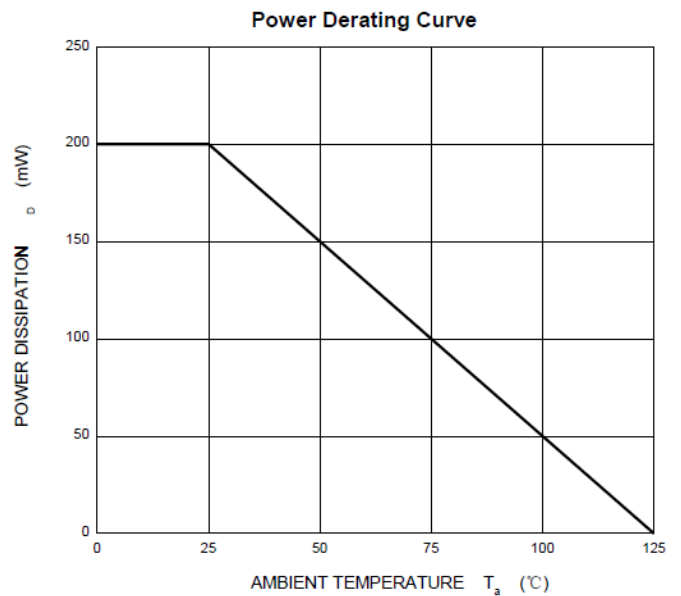
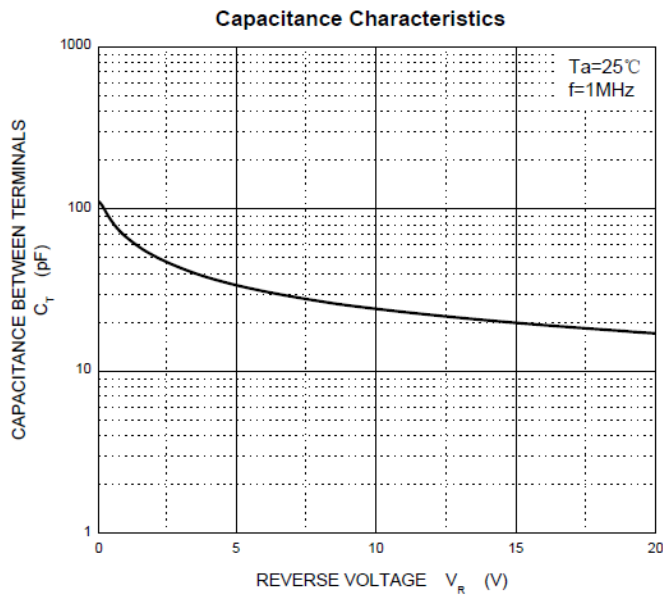
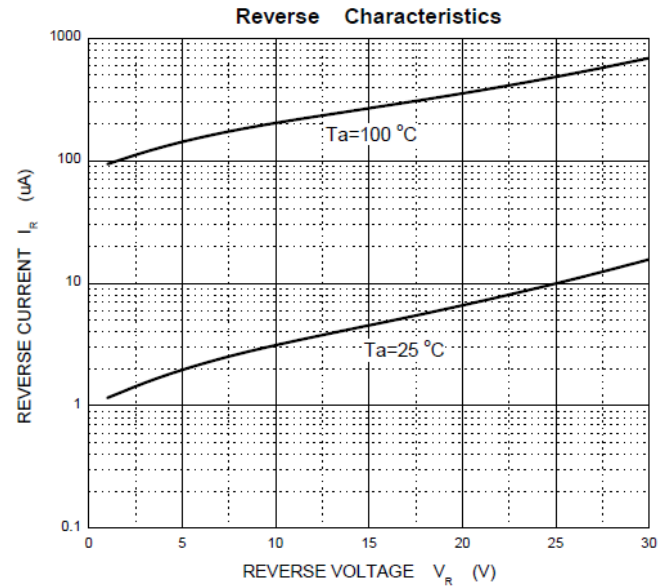
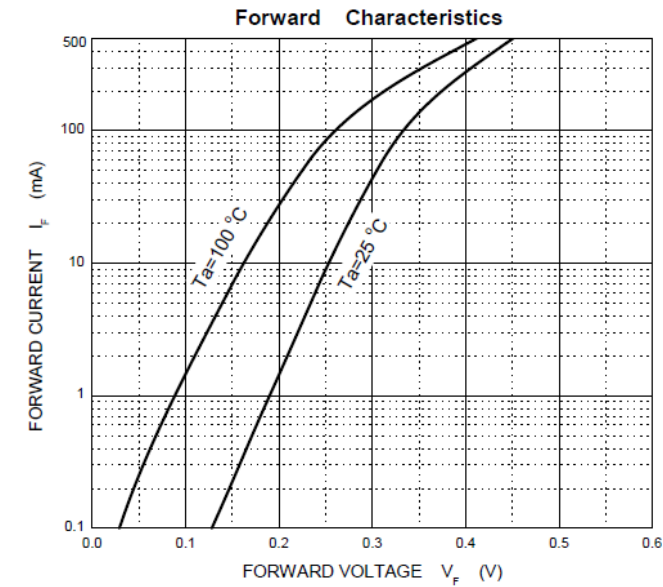


RB551V-30

■ Electrical Characteristics (T_a=25°C Unless otherwise specified)

PARAMETER	Symbol	UNIT	Conditions	Min.	Typ.	Max.
Forward Voltage *	V _F	V	I _F =0.1A	-	-	0.37
			I _F =0.5A	-	-	0.47
Reverse Leakage Current	I _R	μA	V _R =20V	-	-	100

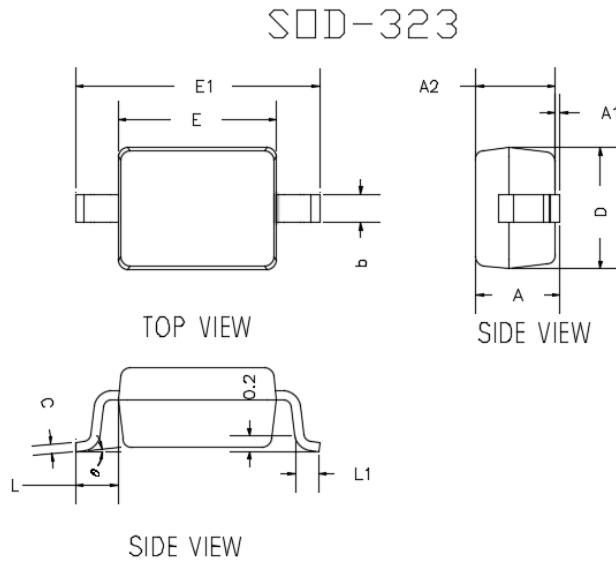
■ Typical Characteristics





RB551V-30

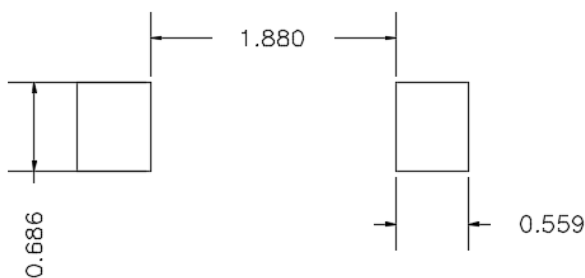
■ Outline Dimensions



DIMENSIONS				
DIM	INCHES		MM	
	MIN	MAX	MIN	MAX
A	---	0.0393	---	1.0000
A1	0.0000	0.0039	0.0000	0.1000
A2	0.0314	0.0354	0.8000	0.9000
b	0.0098	0.0157	0.2500	0.4000
c	0.0031	0.0059	0.0800	0.1500
D	0.0472	0.0551	1.2000	1.4000
E	0.0629	0.0709	1.6000	1.8000
E1	0.0984	0.1063	2.5000	2.7000
L	0.0187TYP		0.475TYP	
L1	0.0098	0.0157	0.250	0.400
θ	0°	8°	0°	8°

- NOTES:
1. All dimensions are in millimeters (mm) unless otherwise specified.
[所有尺寸均以毫米为单位，除非另有说明]
 2. General tolerances: $\pm 0.10\text{mm}$ unless otherwise specified.
[通用公差为 $\pm 0.10\text{mm}$ ，除非另有说明]
 3. Dimensions and tolerances per ASME Y14.5M-2018.
[尺寸和公差遵循 ASME Y14.5M-2018 标准]
 4. All dimensions shown are exclusive of burrs and gate residues.
Burrs and gate vestiges shall not exceed 0.15 mm in maximum.
[所有尺寸均不包括毛刺和浇口残留。毛刺与浇口残留的尺寸最大不得超过 0.15mm]
 5. Dimension b does not include dambar protrusion of max 0.100 mm per side.
[尺寸b不包括单边最大0.100 MM的中筋凸出部分]
 6. Dimensions D and E are the overall extreme outer dimensions of the mold compound. These dimensions exclude mold flash, lead flash, protrusions and burrs but include the maximum allowable mold mismatch.
[D和E是塑封体的外部极限尺寸，不包括包封溢料、内引线溢料、凸出部分以及胶体毛刺，但是包含了包封错位的最大尺寸]
 7. Formed leads shall be planar with respect to one another within a maximum of 0.076 mm relative to the seating plane.
[成型的管脚应为同一平面，共面性最大为0.1mm]

■ Soldering Footprint



UNIT: mm

SUGGESTED SOLDER PAD LAYOUT



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